**Mechanical Properties Characterization Facility**

Wet Lab Test Proposal Description

Name:

Email:

Test Proposal ID:

\*\*\*Please note that **all** relevant areas must be completed, otherwise your proposal may be sent back by the research technician\*\*\*

**Please provide a general description of the work that you’d like to perform, including any cutting, specimen mounting, grinding, polishing, etching, or imaging:**

**Material and Specimen Description:**

(e.g. name or chemical formula, single/polycrystalline/composite, size/shape/dimensions of the piece)

Is this material/specimen heat sensitive? If so at what temperature does damage begin to occur?

**If cutting is requested:**

Please describe the cuts requested (their cross section and dimensions) and their location on the part. A simple schematic with dimensions can be included here, or a separate machine drawing can be attached.

**If preparing a sample for imaging:**

What are the final specimen (or if sample is already mounted – puck) dimensions?

What are you attempting to image and what is the size of the feature of interest?

(e.g. EBSD map of grains approximately 10-30 microns, SEM imaging of grain boundary pinning carbides with an expected size of approximately 1 micron, optical imaging of fatigue crack sized 1-5 mm, etc.)

What preparation steps (mounting, grinding, (electro)polishing, etching, and imaging) would you like to complete in MPRL?

If you know what polishing procedure and etchant formula you would like to use, please list them here. Otherwise, please provide any information you have concerning previous polishing procedures and etchant formulas from the literature that have been used, and please provide a representative image detailing the features of interest if available (either from previous work or from the literature).